

Title (en)
MODULAR FLOOR SYSTEM AND MODULES THEREFOR

Title (de)
MODULARES BODENSYSTEM UND MODULE DAFÜR

Title (fr)
SYSTÈME DE PLANCHER MODULAIRE ET MODULES ASSOCIÉS

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Application
EP 21846480 A 20210718

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• IL 2021050874 W 20210718

Abstract (en)
[origin: WO2022018720A1] A modular raised floor module and raised floor systems constructed therefrom are disclosed. The raised floor module comprising a base floor and a top floor, with a plurality of support pedestals disposed between the base floor and a top floor, wherein the plurality of support pedestals are configured for supporting and leveling the base floor above a bearing surface and for supporting the top floor at a spaced apart relation over the base floor, thereby forming a service space extending between a top face of the base floor and a bottom face of the top floor. The raised floor modules are articulable to one another along their neighboring edges. The base floor can be configured with an inclined surface for draining liquids within the service space towards a liquid collecting portion, for removing liquids from the service space.

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